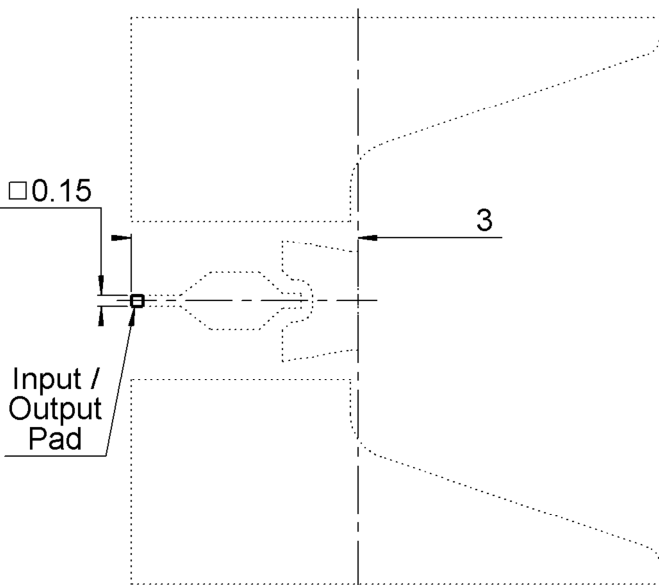




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□0.15

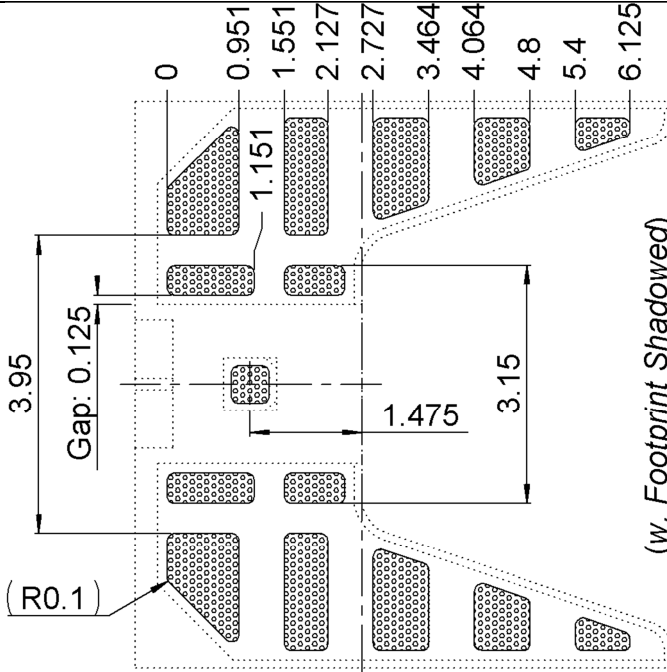
3

Input / Output Pad

(w. Layer 1 Shadowed)

Input / Output Pad

This pad is to be overlapped by the 50 ohms trace going from/towards the chip.



0 0.951 1.551 2.127 2.727 3.464 4.064 4.8 5.4 6.125

1.151

3.95

Gap: 0.125

1.475

3.15

(R0.1)

(w. Footprint Shadowed)

Solder Paste

Thickness between 80 and 100µm recommended.
Use standard lead-free solder paste (SnAgCu)

----- : The layer can expand beyond the footprint limit

See TDS for reflow instructions and temperature profile.

See attached DXF files (R12 version) for exact dimensions and vias position.